

Single 4:1 Low r_{ON} Multiplexers

DESCRIPTION

The DG2034 is a low voltage, low r_{ON} , high bandwidth single 4 to 1 analog multiplexer designed for high performance switching of analog and video signals. Combining low power; fast switching; low on-resistance, flatness and matching; and small physical size, the DG2034 is ideal for portable and battery applications.

Built on Vishay Siliconix's low voltage CMOS process, the DG2034 has an epitaxial layer which prevents latchup. Break-before-make is guaranteed.

FEATURES

- Low voltage operation (1.8 V to 5.5 V)
- Low on-resistance - $r_{DS(on)}$: 4 Ω
- Off-isolation and crosstalk: - 55 dB at 10 MHz
- Fast switch - 25 ns t_{ON}
- Low charge injection - Q_{INJ} : 4.7 pC
- Low power consumption - 4 μ W


RoHS
COMPLIANT

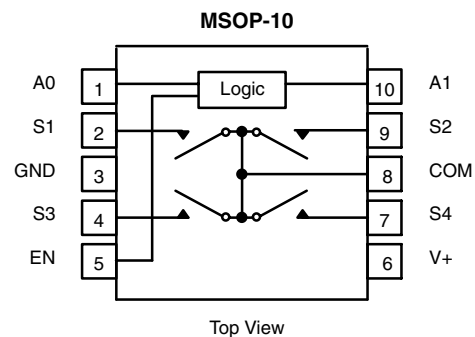
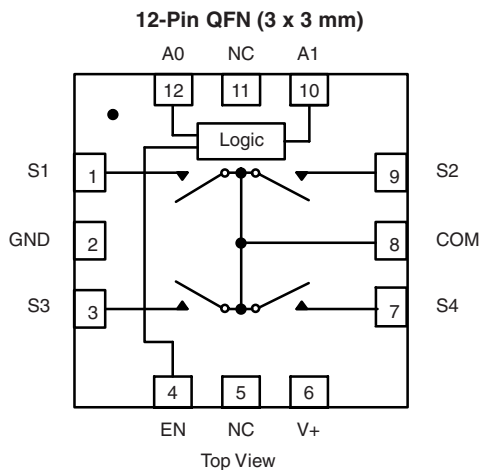
BENEFITS

- High accuracy
- High bandwidth
- TTL and low voltage logic compatibility
- Low power consumption
- Reduced PCB space

APPLICATIONS

- Mixed signal routing
- Portable and battery operated systems
- Low voltage data acquisition
- Modems
- PCMCIA cards

FUNCTIONAL BLOCK DIAGRAM AND PIN CONFIGURATION



TRUTH TABLE

A1	A0	EN	ON Switch
X	X	0	None
0	0	1	S1
0	1	1	S2
1	0	1	S3
1	1	1	S4

ORDERING INFORMATION

Temp Range	Package	Part Number
- 40 °C to 85 °C	MSOP-10	DG2034DQ-T1-E3
	12-pin QFN (3 x 3 mm)	DG2034DN-T1-E4

ABSOLUTE MAXIMUM RATINGS

Parameter	Limit	Unit
Referenced V+ to GND	- 0.3 to + 6	V
A _X , E _N , S _X , COM ^a	- 0.3 to (V+ + 0.3)	
Continuous Current (Any Terminal)	± 50	mA
Peak Current (Pulsed at 1 ms, 10 % duty cycle)	± 100	
Power Dissipation (Packags) ^b	QFN-12 (3 x 3 mm) ^c	mW
	MSOP-10 ^d	
Storage Temperature (D Suffix)	- 65 to 150	°C

Notes:

a. Signals on S_X, D_X, EN or A_X exceeding V+ or V- will be clamped by internal diodes. Limit forward diode current to maximum current ratings.

b. All leads welded or soldered to PC Board.

c. Derate 16.2 mW/°C above 70 °C.

d. Derate 4.0 mW/°C above 70 °C.

SPECIFICATIONS (V+ = 3 V)

Parameter	Symbol	Test Conditions Otherwise Unless Specified V+ = 3 V, ± 10 %, V _{AL} = 0.4 V, V _{AH} = 1.5 V ^e	Temp. ^a	Limits - 40 to 85 °C			Unit
				Min. ^c	Typ. ^b	Max. ^c	
Analog Switch							
Analog Signal Range ^d	V _{ANALOG}		Full	0		V+	V
On-Resistance	r _{ON}	V+ = 2.7 V, V _{COM} = 0.5 V/1.5 V/2.0 V I _S = 10 mA	Room Full		4	7 9	Ω
r _{ON} Match	Δr _{ON}		Room		0.1	0.3	
r _{ON} Flatness ^{d,f}	r _{ON} Flatness		Room		0.3	1.5	
Off Leakage Current ^g	I _{S(off)}	V+ = 3.3 V, V _S = 1 V/3 V V _{COM} = 3 V/1 V, V _{EN} = 0 V	Room Full	- 1 - 10	0.3	1 10	nA
COM Off Leakage Current ^g	I _{COM(off)}		Room Full	- 1 - 10	0.3	1 10	
Channel-On Leakage Current ^g	I _{COM(on)}	V+ = 3.3 V V _{COM} = V _S = 1 V/3 V	Room Full	- 1 - 10	0.3	1 10	
Digital Control							
Input Current ^d	I _A or I _{EN}	V _{A/EN} = 0 or V+, See Truth Table	Full	- 1.0		1.0	μA
Input High Voltage ^d	V _{AH} or V _{ENH}		Full	1.5			V
Input Low Voltage ^d	V _{AL} or V _{ENL}		Full			0.4	
Dynamic Characteristics							
Turn-On Time	t _{ON}	V _S = 1.5 V, R _L = 300 Ω	Room Full		25	35 45	ns
Turn-Off Time	t _{OFF}		Room Full		15	25 35	
Break-Before-Make Time ^d	t _D		Room		10.5		
Transition Time	t _{trans}	V _S = 1.5 V/0 V, V _S = 0 V/1.5 V, R _L = 300 Ω	Room Full		30	45 55	
Charge Injection ^d	Q _{INJ}	C _L = 1 nF, V _{gen} = 0 V, R _{gen} = 0 Ω	Room		- 4.7		pC
Off-Isolation ^d	OIRR	R _L = 50 Ω, C _L = 5 pF	f = 1 MHz Room		- 73		dB
			f = 10 MHz Room		- 54		
Channel-to-Channel Crosstalk ^d	X _{TALK}	R _L = 50 Ω, C _L = 5 pF	f = 1 MHz Room		- 77		
			f = 10 MHz Room		- 59		
Off Capacitance ^d	C _{S(off)}	V+ = 2.7 V, f = 1 MHz	Room		14		pF
COM Off Capacitance ^d	C _{COM(off)}		Room		46		
COM On Capacitance ^d	C _{COM(on)}		Room		67		
Power Supply							
Power Supply Range	V+			2.7		3.3	V
Power Supply Current ^d	I+	V+ = 3.3 V, V _{A/EN} = 0 or 3.3 V, See Truth Table	Full			1.0	μA



SPECIFICATIONS (V+ = 5 V)								
Parameter	Symbol	Test Conditions Otherwise Unless Specified V+ = 3 V, ± 10 %, V _{AL} = 0.8 V or V _{AH} = 2.4 V ^e		Temp. ^a	Limits - 40 to 85 °C			Unit
					Min. ^c	Typ. ^b	Max. ^c	
Analog Switch								
Analog Signal Range ^d	V _{ANALOG}	V+ = 4.5 V, V _{COM} = 1.5 V/2.5 V/3.5 V I _S = 10 mA		Full	0		V+	V
On-Resistance	r _{ON}			Room Full		3	5.5 7	Ω
r _{ON} Match	Δr _{ON}			Room		0.16	0.5	
r _{ON} Flatness ^{d,f}	r _{ON} Flatness			Room		0.6	1.5	
Off Leakage Current	I _{S(off)}	V+ = 5.5 V, V _S = 1 V/4.5 V V _{COM} = 4.5 V/1 V, V _{EN} = 0 V		Room Full	- 1 - 10	0.5	1 10	nA
COM Off Leakage Current	I _{COM(off)}			Room Full	- 1 - 10	0.5	1 10	
Channel-On Leakage Current	I _{COM(on)}	V+ = 5.5 V, V _{COM} = V _S = 1 V/4.5 V		Room Full	- 1 - 10	0.5	1 10	
Digital Control								
Input Current ^d	I _{AH} or I _{ENH}	V _A or V _{EN} = 0 or V+, See Truth Table		Full	- 1.0		1.0	μA
Input High Voltage ^d	V _{AH} or V _{ENH}			Full	2.4			V
Input Low Voltage ^d	V _{AL} or V _{ENL}			Full			0.8	
Dynamic Characteristics								
Turn-On Time	t _{ON}	V _S = 3.0 V, R _L = 300 Ω		Room Full		18	30 40	ns
Turn-Off Time	t _{OFF}			Room Full		12	20 30	
Break-Before-Make Time ^d	t _D			Room		10.5		
Transition Time	t _{trans}	V _S = 3 V/0 V, V _S = 0 V/3 V, R _L = 300 Ω		Room Full		25	40 50	
Off-Isolation ^d	OIRR	R _L = 50 Ω, C _L = 5 p	f = 1 MHz	Room		- 73		dB
			f = 10 MHz	Room		- 53.5		
Channel-to-Channel Crosstalk ^d	X _{TALK}	R _L = 50 Ω, C _L = 5 pF	f = 1 MHz	Room		- 77		
			f = 10 MHz	Room		- 60.2		
Charge Injection ^d	Q _{INJ}	C _L = 1 nF, V _{gen} = 0 V, R _{gen} = 0 Ω		Room		- 4.4		pC
Off Capacitance ^d	C _{S(off)}	V+ = 5 V, f = 1 MHz		Room		13		pF
COM Off Capacitance ^d	C _{COM(off)}			Room		43		
COM On Capacitance ^d	C _{COM(on)}			Room		64		
Power Supply								
Power Supply Range	V+				4.5		5.5	V
Power Supply Current	I+	V+ = 5.5 V, V _{A/EN} = 0 or 5.5 V, See Truth Table		Full			1.0	μA

Notes:

a. Room = 25 °C, Full = as determined by the operating suffix.

b. Typical values are for design aid only, not guaranteed nor subject to production testing.

c. The algebraic convention whereby the most negative value is a minimum and the most positive a maximum, is used in this data sheet.

d. Guarantee by design, not subjected to production test.

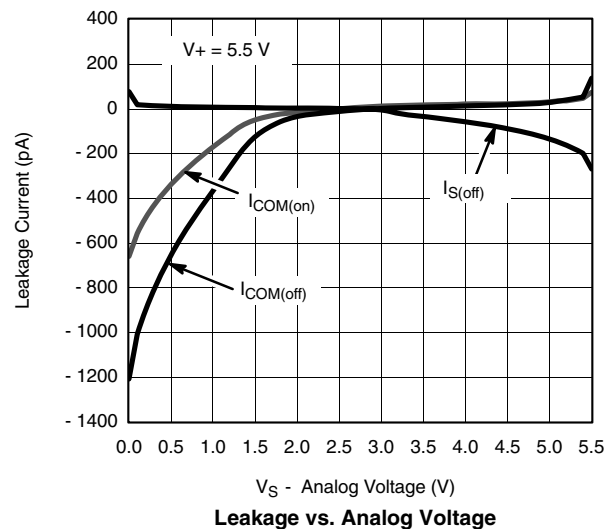
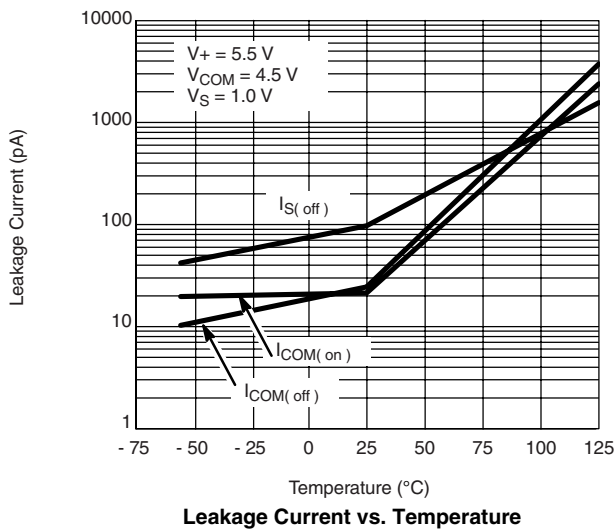
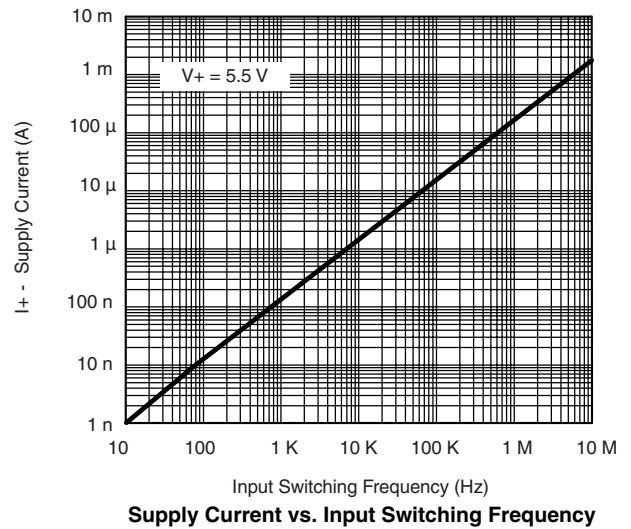
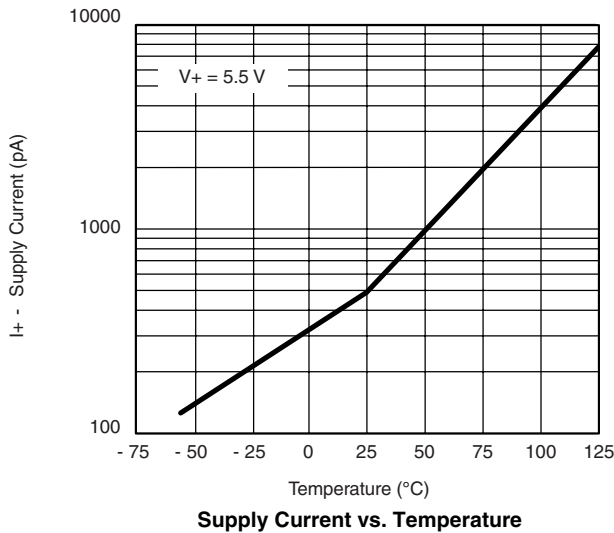
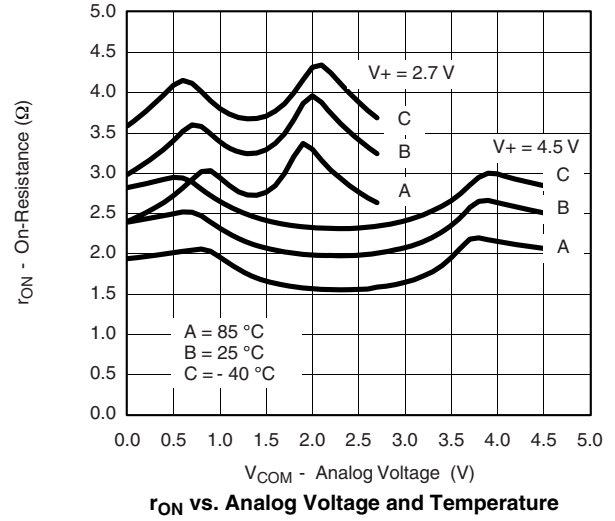
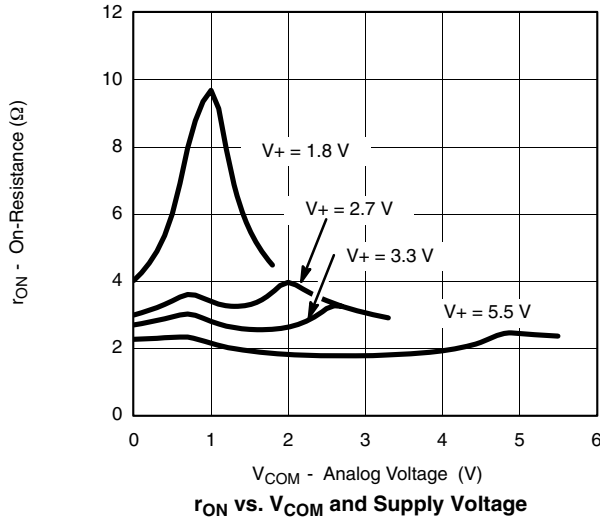
e. V_A, E_N = input voltage to perform proper function.

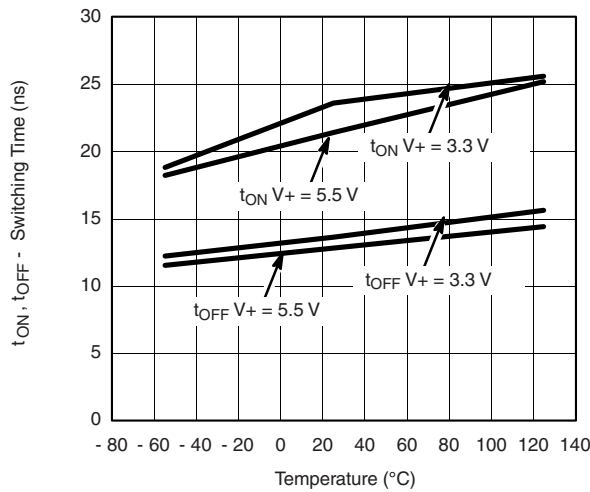
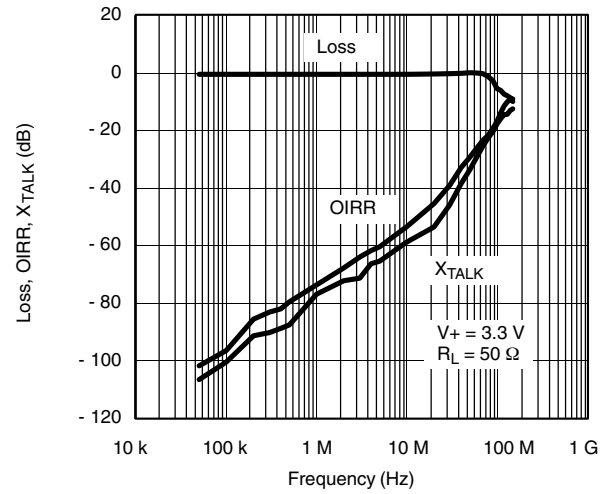
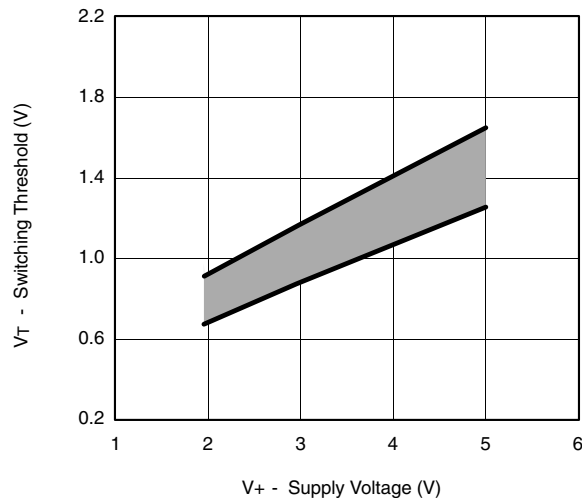
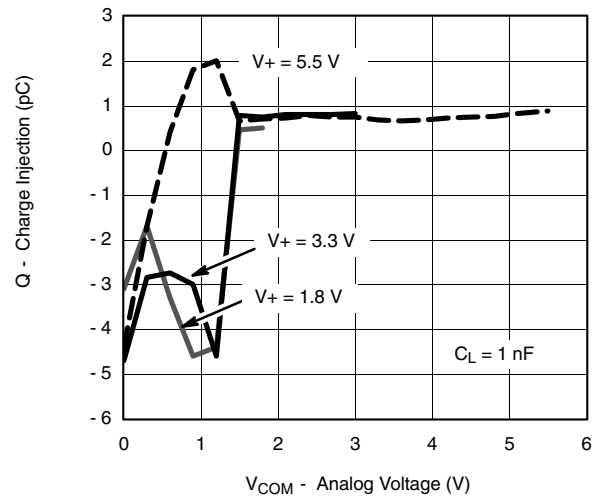
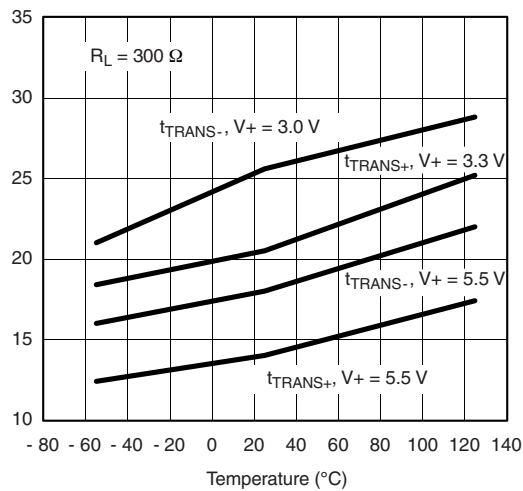
f. Difference of min and max values.

g. Guaranteed by 5 V testing.

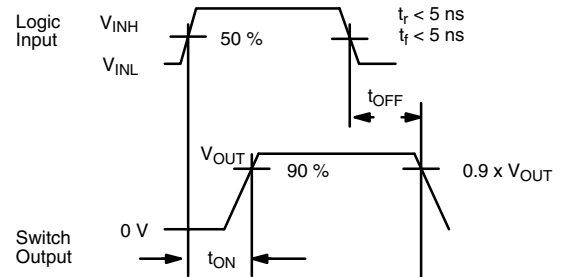
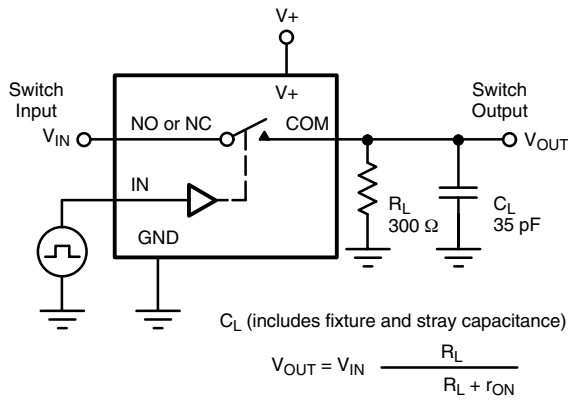
Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted

Switching Time vs. Temperature

Insertion Loss, Off-Isolation Crosstalk vs. Frequency

Switching Threshold vs. Supply Voltage

Charge Injection vs. Analog Voltage

Transition Time vs. Temperature

TEST CIRCUITS



Note: Logic input waveform is inverted for switches that have the opposite logic sense control

Figure 1. Switching Time

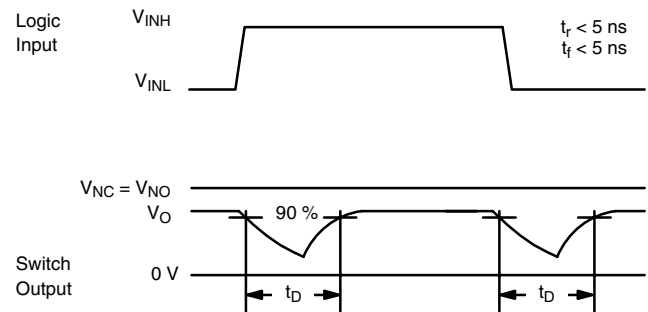
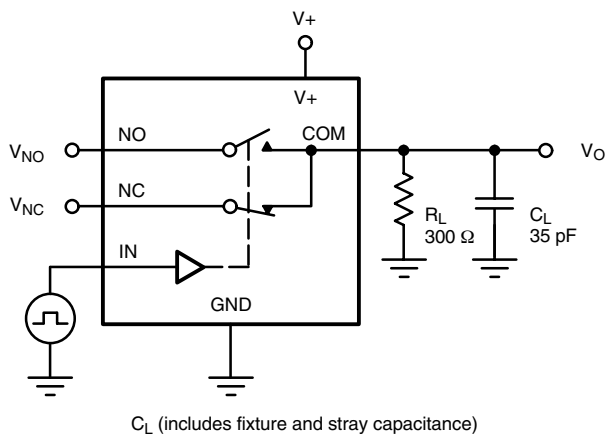


Figure 2. Break-Before-Make

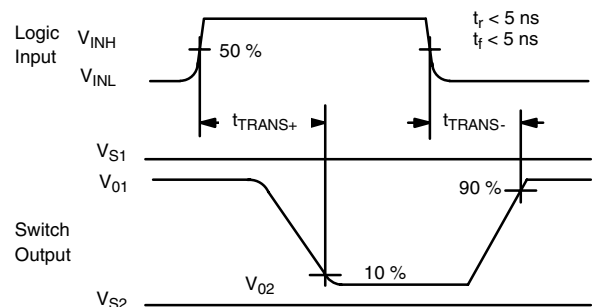
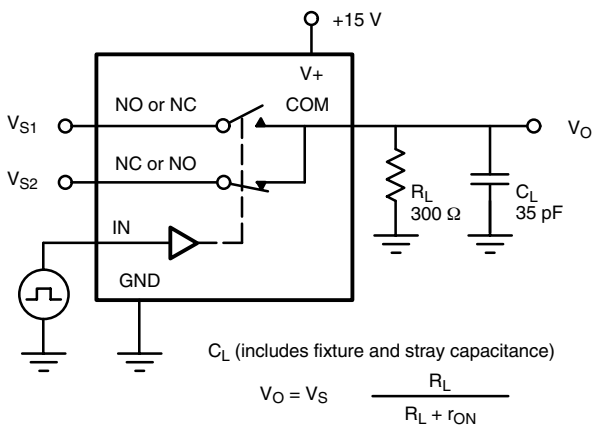
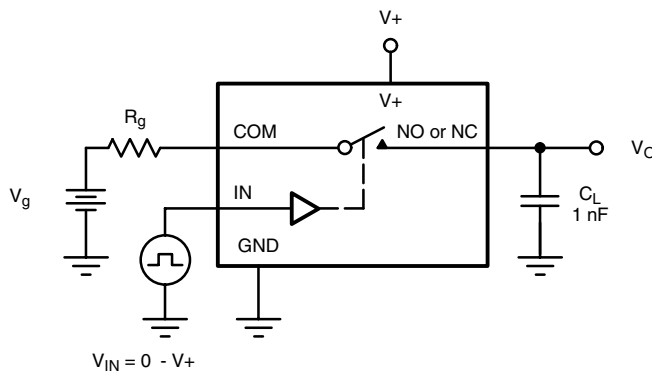
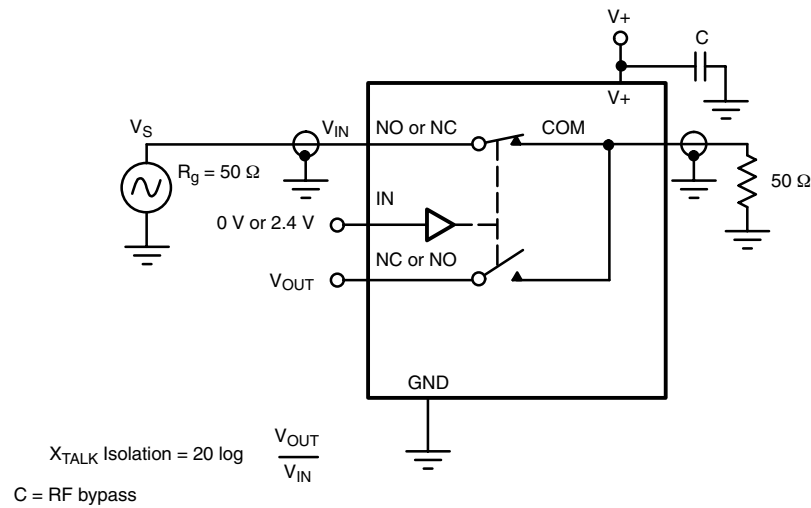
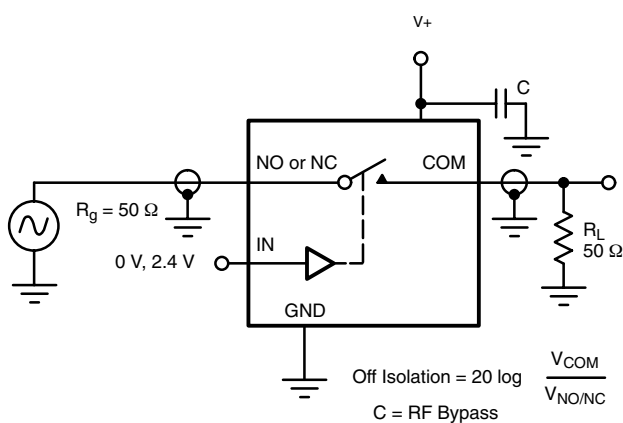
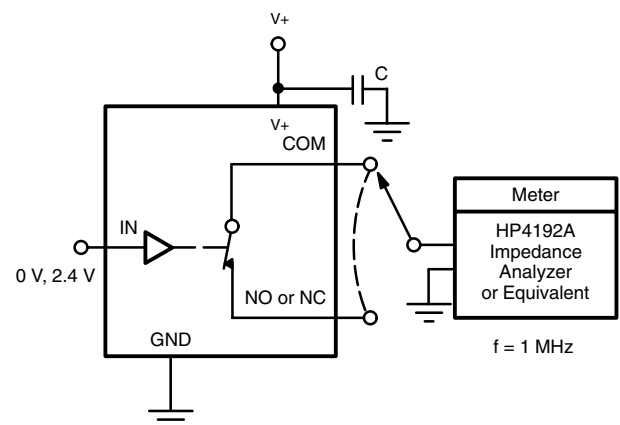


Figure 3. Transition Time

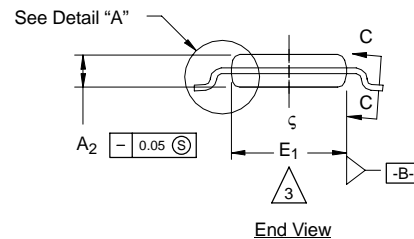
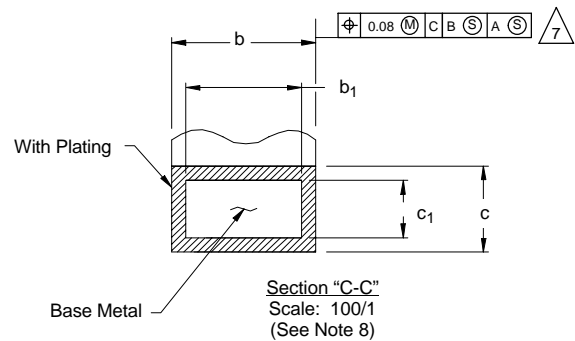
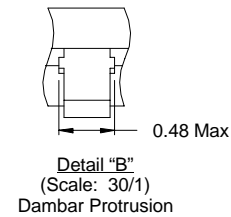
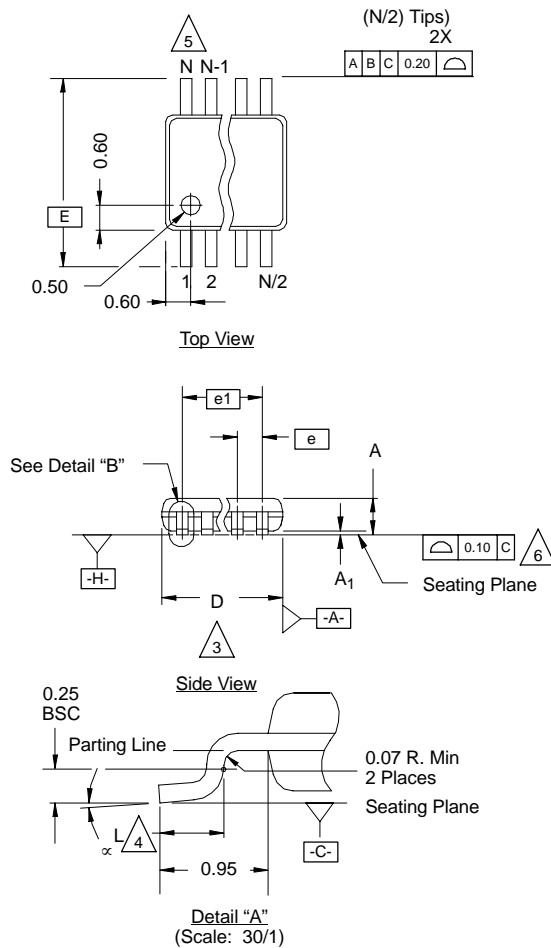
TEST CIRCUITS

Figure 4. Charge Injection

Figure 5. Crosstalk

Figure 6. Off Isolation

Figure 7. Source/Drain Capacitances

Vishay Siliconix maintains worldwide manufacturing capability. Products may be manufactured at one of several qualified locations. Reliability data for Silicon Technology and Package Reliability represent a composite of all qualified locations. For related documents such as package/tape drawings, part marking, and reliability data, see <http://www.vishay.com/ppg?72418>.



MSOP: 10-LEADS

JEDEC Part Number: MO-187, (Variation AA and BA)



NOTES:

- Die thickness allowable is 0.203 ± 0.0127 .
- Dimensioning and tolerances per ANSI.Y14.5M-1994.
- Dimensions "D" and "E₁" do not include mold flash or protrusions, and are measured at Datum plane $\boxed{-H-}$, mold flash or protrusions shall not exceed 0.15 mm per side.
- Dimension is the length of terminal for soldering to a substrate.
- Terminal positions are shown for reference only.
- Formed leads shall be planar with respect to one another within 0.10 mm at seating plane.
- The lead width dimension does not include Dambar protrusion. Allowable Dambar protrusion shall be 0.08 mm total in excess of the lead width dimension at maximum material condition. Dambar cannot be located on the lower radius or the lead foot. Minimum space between protrusions and an adjacent lead to be 0.14 mm. See detail "B" and Section "C-C".
- Section "C-C" to be determined at 0.10 mm to 0.25 mm from the lead tip.
- Controlling dimension: millimeters.
- This part is compliant with JEDEC registration MO-187, variation AA and BA.
- Datums $\boxed{-A-}$ and $\boxed{-B-}$ to be determined Datum plane $\boxed{-H-}$.
- Exposed pad area in bottom side is the same as the leadframe pad size.

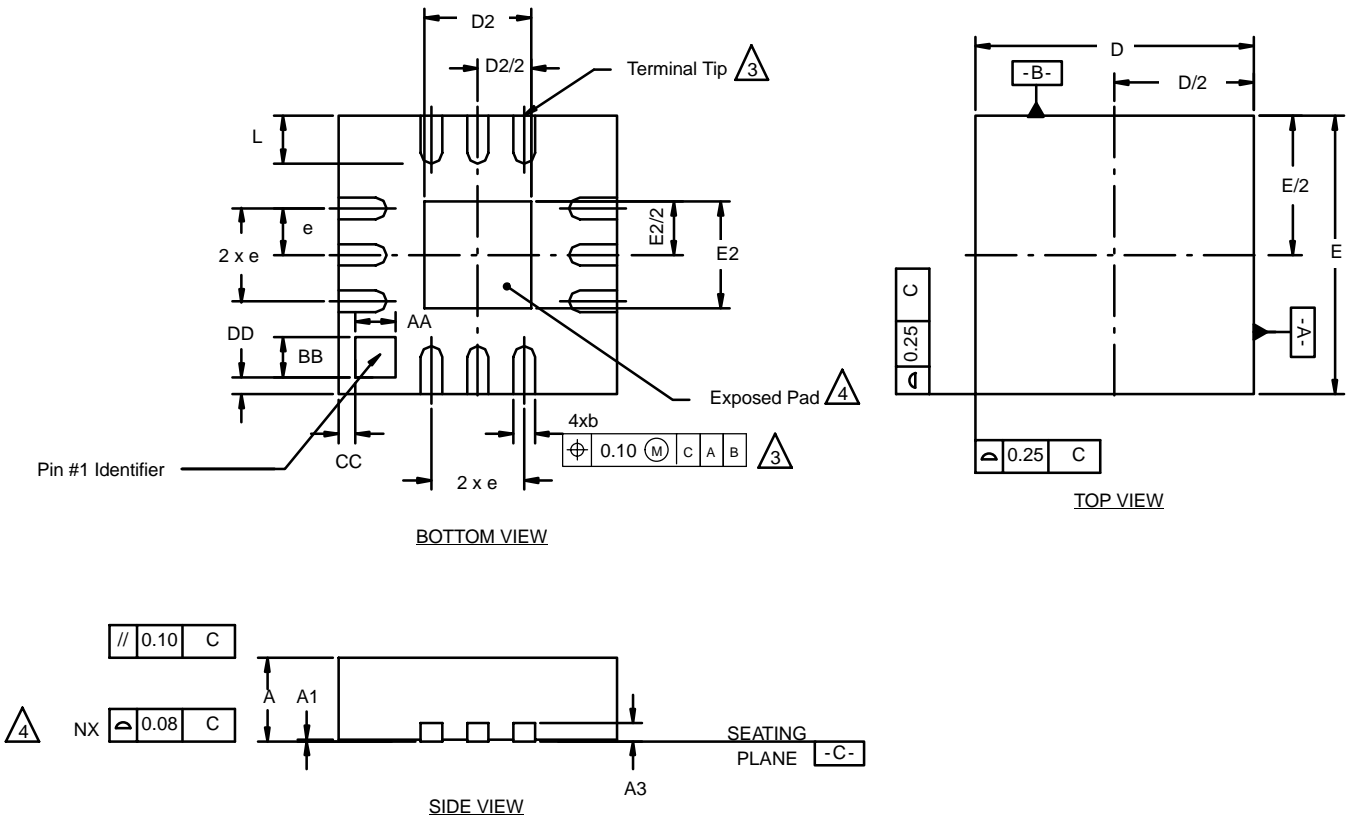
N = 10L

Dim	MILLIMETERS			Note
	Min	Nom	Max	
A	-	-	1.10	
A ₁	0.05	0.10	0.15	
A ₂	0.75	0.85	0.95	
b	0.17	-	0.27	8
b ₁	0.17	0.20	0.23	8
c	0.13	-	0.23	
c ₁	0.13	0.15	0.18	
D	3.00 BSC			3
E	4.90 BSC			
E ₁	2.90	3.00	3.10	3
e	0.50 BSC			
e ₁	2.00 BSC			
L	0.40	0.55	0.70	4
N	10			5
α	0°	4°	6°	

ECN: T-02080—Rev. C, 15-Jul-02
DWG: 5867



QFN-12 LEAD (3 X 3)



NOTES:

1. All dimensions are in millimeters.
2. N is the total number of terminals.
3. Dimension b applies to metallized terminal and is measured between 0.25 and 0.30 mm from terminal tip.
4. Coplanarity applies to the exposed heat sink slug as well as the terminal.
5. The pin #1 identifier may be either a mold or marked feature, it must be located within the zone indicated.

Dim	MILLIMETERS			INCHES		
	Min	Nom	Max	Min	Nom	Max
A	0.80	0.90	1.00	0.032	0.035	0.039
b	0.18	0.23	0.30	0.007	0.009	0.012
D	3.00 BSC			0.118 BSC		
D2	1.00	1.15	1.25	0.039	0.045	0.049
E	3.00 BSC			0.118 BSC		
E2	1.00	1.15	1.25	0.039	0.045	0.049
e	0.50 BSC			0.02 BSC		
L	0.45	0.55	0.65	0.018	0.022	0.026
AA	0.435			0.017		
BB	0.435			0.017		
CC	0.18			0.007		
DD	0.18			0.007		
ECN: C-03092—Rev. A, 14-Apr-03 DWG: 5898						



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Please note that some Vishay documentation may still make reference to RoHS Directive 2002/95/EC. We confirm that all the products identified as being compliant to Directive 2002/95/EC conform to Directive 2011/65/EU.

Vishay Intertechnology, Inc. hereby certifies that all its products that are identified as Halogen-Free follow Halogen-Free requirements as per JEDEC JS709A standards. Please note that some Vishay documentation may still make reference to the IEC 61249-2-21 definition. We confirm that all the products identified as being compliant to IEC 61249-2-21 conform to JEDEC JS709A standards.